ASSOCIATION C	Material Composition © Copyright 2005. Il international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both	This docume level parts, the	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute								ials and Mfg Information				
Supplier I	Information													
Company name*			Company unique ID			ī	Unique ID Authority				Response Date*			
onsemi										2025-06-07				
Contact Nan	me	Title - Contact				Phone - Contact*				Email - Contact*				
Product-En	v-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized 1	Representative*	Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
I	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	te Versio	ersion Manufacturing Site			Weight*	UOM	Unit Type
		NVTFS002N04CLTA T6 40V LL N		T6 40V LL Nch us	ı u8FL		2025-06-07		1	MY1		27.452936	mg	Each
Manufact	turing Proccess Informat	tion												
Т	Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperat		ture Max Time at Peak Tempera		ure Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed			CU Alloy 1			260	260 C 30		30	secon	ds 3			
Comments														
vel 1 - max	ximum time at peak temperatu	re during sol	dering is 10-3	0 seconds										
or more in	formation regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.378234	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3688	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.152807	mg	Supplier	Silicon (Si)	7440-21-3		0.1528	mg
Lead Frame	11.4444	mg	Supplier	Silver (Ag)	7440-22-4		0.2197	mg
			Supplier	Iron (Fe)	7439-89-6		0.0103	mg
			Supplier	Copper (Cu)	7440-50-8		11.2132	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0011	mg
Mold Compound-Black	12.6623	mg		Epoxy resin	proprietary data		0.9497	mg
			Supplier	Phenolic Resin	Proprietary Data		0.3166	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.9497	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0633	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		10.3831	mg
Plating	0.951436	mg	Supplier	Tin (Sn)	7440-31-5		0.9514	mg
Solder Paste	1.84959	mg	Supplier	Silver (Ag)	7440-22-4		0.0462	mg
			A	Lead (Pb)	7439-92-1	7a	1.7109	mg
			Supplier	Tin (Sn)	7440-31-5		0.0925	mg
Wire Bond - Cu	0.01417	mg	Supplier	Copper (Cu)	7440-50-8		0.0142	mg